

Notice of References Cited	Application/Control No. 10/706,090	Applicant(s)/Patent Under Reexamination SUGAMOTO ET AL.	
	Examiner Granvill D Lee, Jr	Art Unit 2825	Page 1 of 1

U.S. PATENT DOCUMENTS

*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Name	Classification
	A	US-2002/0137343	09-2002	Wang et al.	438/689
	B	US-2003/0113941	06-2003	Naruoka, Hideki	438/14
	C	US-6,638,357	10-2003	Mule'Stagno et al.	117/2
	D	US-6,391,662	05-2002	Mule'Stagno et al.	438/8
	E	US-6,364,947	04-2002	Iida et al.	117/206
	F	US-5,968,264	10-1999	Iida et al.	117/30
	G	US-5,688,319	11-1997	Fusegawa et al.	117/13
	H	US-6,277,193	08-2001	Sadamitsu et al.	117/88
	I	US-5,534,112	07-1996	Fusegawa et al.	438/16
	J	US-			
	K	US-			
	L	US-			
	M	US-			

FOREIGN PATENT DOCUMENTS

*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Country	Name	Classification
	N					
	O					
	P					
	Q					
	R					
	S					
	T					

NON-PATENT DOCUMENTS

*		Include as applicable: Author, Title Date, Publisher, Edition or Volume, Pertinent Pages)
	U	Younan et al. "Studies on stacking faults and crystalline defects in fabrication silicon wafer substrate" Semiconductor electronics, 1998 proceedings. 1998 IEEE international conference, 24 Nov. 1998, pg. 1-8.
	V	Younan et al. "Improvement of 155 Wright etch and its application in failure analysis in line qbd failure in wafer fabrication" Semiconductor electronics, 1998 proceedings. 1998 IEEE international conference, 21 Dec. 2002, pg. 188-190..
	W	
	X	

*A copy of this reference is not being furnished with this Office action. (See MPEP § 707.05(a).)
Dates in MM-YYYY format are publication dates. Classifications may be US or foreign.